Materials Declaration

Package	QSOP
Body Size/Pitch	150 mils
LeadCount	24
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	7.31 E-03	51043
SiO2 Filler	85	6.22 E-02	433862
Phenol Resin	3	2.19 E-03	15313
Antimony_Sb2O3	1.5	1.10 E-03	7656
Brominated Resin	0.5	3.66 E-04	2552

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	5.89 E-02	411419
Fe	2.35	1.42 E-03	9916
P	0.03	1.81 E-05	127
Zn	0.12	7.26 E-05	506

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	6.68 E-04	4659

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	3.23 E-03	22543

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	6.30 E-04	4397

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	4.85 E-03	33819

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.84 E-05	547
Ag Filler	75	2.35 E-04	1642

Package Totals

Weight (g)	PPM
1.43 E-01	1000000

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

AMK-RQ-B

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability tc
any inaccuracy of such information.

ANALOG DEVICES

ADI Proprietary

11/23/05

Materials Declaration

Package	QSOP
Body Size/Pitch	150 mils
LeadCount	24
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	7.31 E-03	51200
SiO2 Filler	85	6.22 E-02	435198
Phenol Resin	3	2.19 E-03	15360
Antimony_Sb2O3	1.5	1.10 E-03	7680
Brominated Resin	0.5	3.66 E-04	2560

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.5	5.89 E-02	412686
Fe	2.35	1.42 E-03	9947
P	0.03	1.81 E-05	127
Zn	0.12	7.26 E-05	508

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	6.68 E-04	4673

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.55 E-03	17852
Pb	15	4.50 E-04	3150

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	4.20 E-04	2940

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	4.85 E-03	33923

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.84 E-05	549
Ag Filler	75	2.35 E-04	1647

Molding Compound

Item	PPM	Method
Pb	<2	US EPA method #3052 & 6010B
Cd	Not Detected	BS EN 1122:2001 ICP AES
Hg	<2	US EPA method #3052 & 7471A
Cr+6	<2	US EPA method #3060A & 6010B

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
1.43 E-01	1000000

AMK-RQ-A

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ANALOG DEVICES

ADI Proprietary

11/23/05